dielectric member 234 and preferably having a second conducting surface 242 exposed to the plasma zone 206. An electrode voltage supply 244 is provided for maintaining the power electrode 238, and the primary and secondary bias electrodes 230, 240 at different electrical potentials relative to one another. Preferably, the power electrode 238 is used to carry both a DC chucking voltage and the RF bias voltage. The voltage supply 244 includes an AC voltage supply for providing a plasma generating RF voltage to the power electrode 238, and a DC voltage supply for providing a chucking voltage to the electrode 238. A separate DC voltage is applied to the electrode 238 to form an electrostatic charge that holds the substrate to the chuck. The RF power is coupled to a bridge circuit and a DC converter to provide DC chucking power to the electrode. The voltage supply 244 can also include a system controller for controlling the operation of the electrode by directing a DC current, and RF current, or both, to the electrode for chucking and dechucking the substrate 118 and for generating plasma in the process chamber 202.

A1

IN THE DRAWINGS

Please amend figure 2 according to the red inked marked figure 2 enclosed.

A2

REMARKS

The above amendments have been made to correct minor inadvertent grammatical and formal errors in the specification and drawings; no new matter has been added. Specifically, the change in legends in paragraph 19 (namely, voltage supply 220 to voltage supply 244) is necessary to conform the written specification to Figure 2. Figure 2 shows a voltage supply 244 at the bottom of the figure. Additionally, figure legend "30" shown in Figure 2 should be "118" to denote the substrate that is received upon primary bias electrode surface 236. Support for this correction can be shown at paragraph 19, sentence number 4 which says, "(a) unitary monolithic dielectric member 234 positioned directly below the primary bias electrode 230 has a receiving surface 236 for receiving a substrate 118 thereon". To expedite processing of this Preliminary Amendment and submission of correct formal